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DATA SHEET

BFS17W
NPN 1 GHz wideband transistor

Product specification
Supersedes data of November 1992

1995 Sep 04

NPN 1 GHz wideband transistor BFS17W

APPLICATIONS

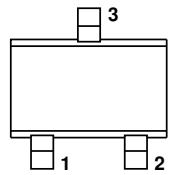
Primarily intended as a mixer, oscillator and IF amplifier in UHF and VHF tuners.

DESCRIPTION

Silicon NPN transistor in a plastic SOT323 (S-mini) package. The BFS17W uses the same crystal as the SOT23 version, BFS17.

PINNING

PIN	DESCRIPTION
1	base
2	emitter
3	collector



Top view MBC870

Marking code: E1

Fig.1 SOT323

QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V_{CBO}	collector-base voltage		–	–	25	V
V_{CEO}	collector-emitter voltage		–	–	15	V
I_C	DC collector current		–	–	50	mA
P_{tot}	total power dissipation	up to T_s = 118 °C; note 1	–	–	300	mW
h_{FE}	DC current gain	I_C = 2 mA; V_{CE} = 1 V	25	90	–	
f_T	transition frequency	I_C = 25 mA; V_{CE} = 5 V	–	1.6	–	GHz
C_c	collector capacitance	I_E = 0; V_{CB} = 10 V; f = 1 MHz	–	0.8	1.5	pF
C_{re}	feedback capacitance	I_C = 1 mA; V_{CE} = 5 V; f = 1 MHz	–	0.75	–	pF
T_j	junction temperature		–	–	175	°C

Note

1. T_s is the temperature at the soldering point of the collector pin.

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{CBO}	collector-base voltage	open emitter	–	25	V
V_{CEO}	collector-emitter voltage	open base	–	15	V
V_{EBO}	emitter-base voltage	open collector	–	2.5	V
I_C	collector current (DC)		–	50	mA
P_{tot}	total power dissipation	T_s = 118 °C; note 1	–	300	mW
T_{stg}	storage temperature		−65	+150	°C
T_j	junction temperature		–	175	°C

Note

1. T_s is the temperature at the soldering point of the collector pin.

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th\ j\text{-}s}$	thermal resistance from junction to soldering point	up to T_s = 118 °C; note 1	190	K/W

Note

1. T_s is the temperature at the soldering point of the collector pin.

CHARACTERISTICS

T_j = 25 °C (unless otherwise specified).

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I_{CBO}	collector cut-off current	I_E = 0; V_{CB} = 10 V	–	–	10	nA
h_{FE}	DC current gain	I_C = 2 mA; V_{CE} = 1 V	25	90	–	
f_T	transition frequency	I_C = 25 mA; V_{CE} = 5 V; f = 500 MHz	–	1.6	–	GHz
C_c	collector capacitance	$I_E = i_e$ = 0; V_{CB} = 10 V; f = 1 MHz	–	0.8	1.5	pF
C_e	emitter capacitance	$I_C = i_c$ = 0; V_{EB} = 0.5 V; f = 1 MHz	–	2	–	pF
C_{re}	feedback capacitance	$I_B = i_b$ = 0; V_{CE} = 5 V; f = 1 MHz; T_{amb} = 25 °C	–	0.75	–	pF
F	noise figure	I_C = 2 mA; V_{CE} = 5 V; f = 500 MHz; $\Gamma_S = \Gamma_{opt}$	–	4.5	–	dB

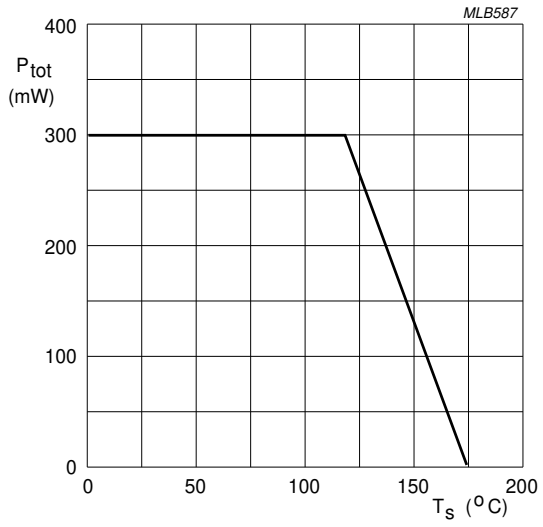
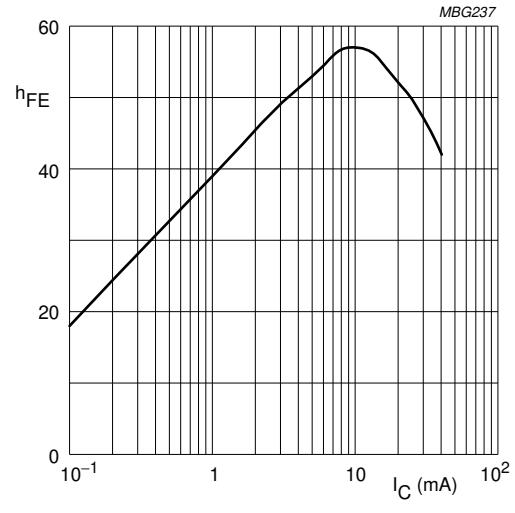
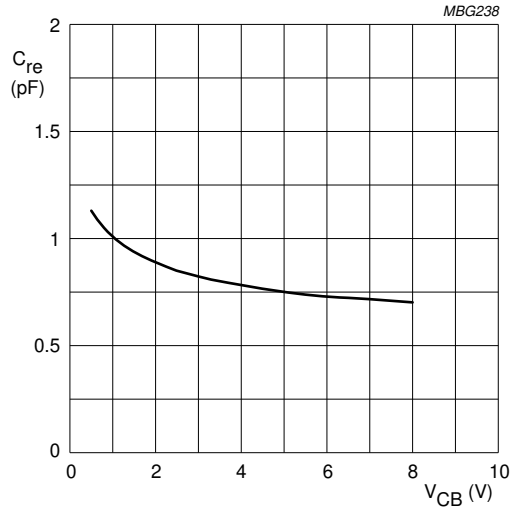


Fig.2 Power derating curve.



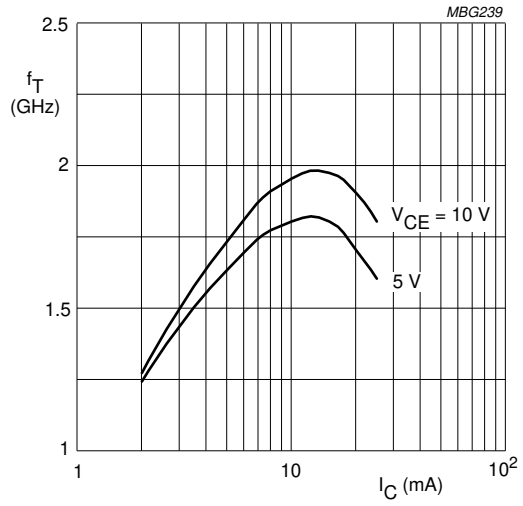
V_{CE} = 1 V.

Fig.3 DC current gain as a function of collector current; typical values.



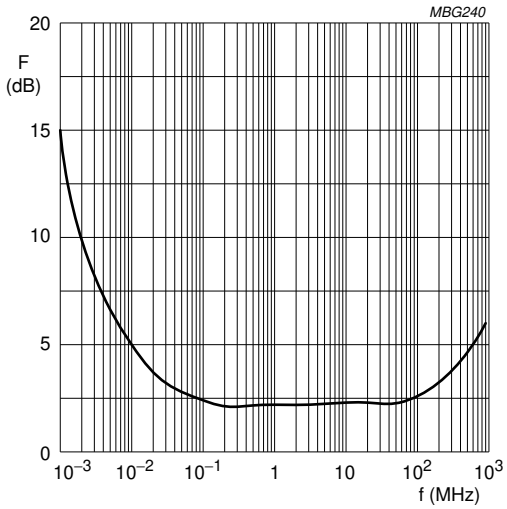
$I_B = i_b = 0$; f = 1 MHz.

Fig.4 Feedback capacitance as a function of collector-base voltage; typical values.



T_{amb} = 25 °C; f = 500 MHz.

Fig.5 Transition frequency as a function of collector current; typical values.

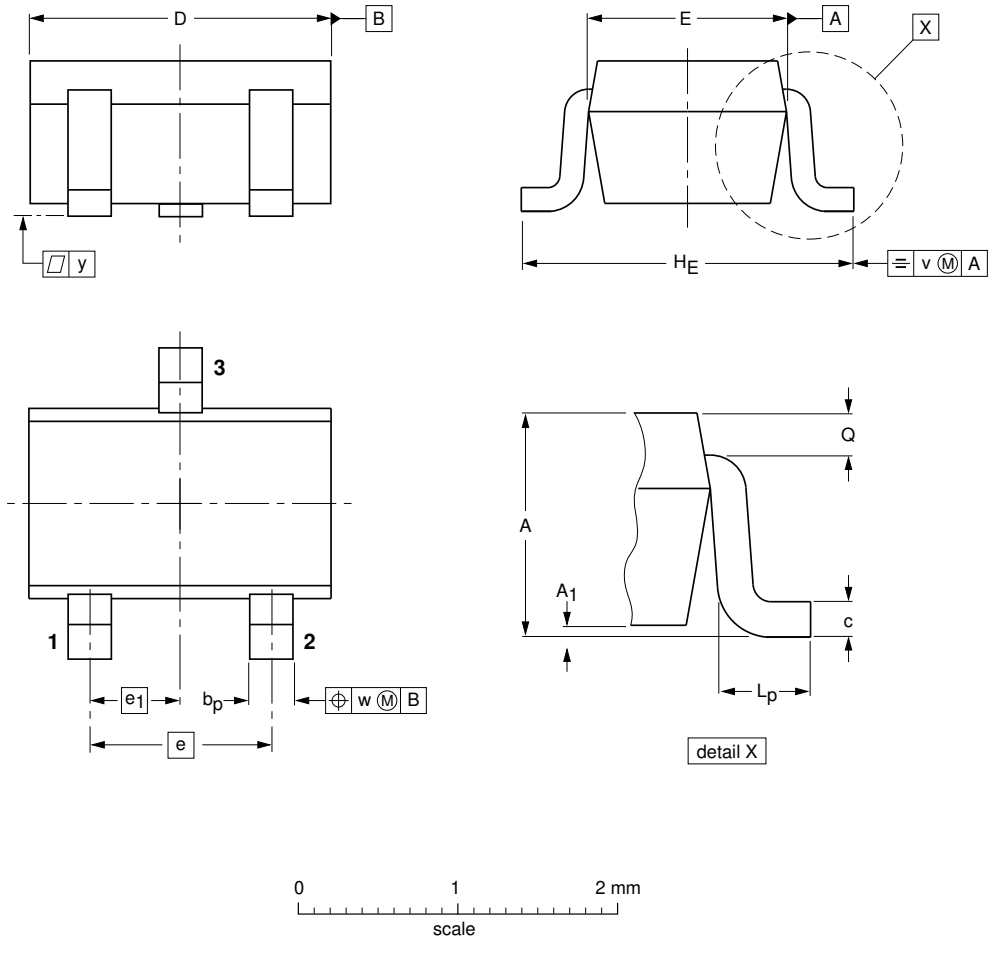


V_{CE} = 10 V.

Fig.6 Minimum noise figure as function of frequency; typical values.

PACKAGE OUTLINE

Plastic surface-mounted package; 3 leads **SOT323**



DIMENSIONS (mm are the original dimensions)

UNIT	A	A_1 max	b_p	c	D	E	e	e_1	H_E	L_p	Q	v	w
mm	1.1 0.8	0.1	0.4 0.3	0.25 0.10	2.2 1.8	1.35 1.15	1.3	0.65	2.2 2.0	0.45 0.15	0.23 0.13	0.2	0.2

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT323			SC-70			~~04-11-04~~ 06-03-16

DATA SHEET STATUS

DOCUMENT STATUS[1]	PRODUCT STATUS[2]	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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